



#1415-203

PATENT**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Cabuz et al.

Serial No.: 09/749,171 Examiner: Simkovic, Viktor

Filed: December 27, 2000 Group Art Unit: 2812

For: THIN SILICON MICROMACHINED STRUCTURES

Docket No.: 1100.1116101 (H16-26635)

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INFORMATION DISCLOSURE STATEMENT AFTER MAILING DATE OF A FINAL ACTION (37 CFR 1.97(d))Assistant Commissioner for Patents
Washington, D.C. 20231

CERTIFICATE UNDER 37 C.F.R. 1.10: The undersigned hereby certifies that this paper or papers, as described herein, are being deposited in the United States Postal Service, "Express Mail Post Office to Addressee" having an Express Mail mailing label number of: EV091136155US, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C., 20231 on this 22 day of January, 2003.

By Lynn Thompson
Lynn Thompson

Dear Sir:

Pursuant to the obligations of candor and good faith imposed by 37 C.F.R 1.56, the documents listed on the attached PTO-1449 are hereby disclosed.

No representation is intended to be made hereby that any of the cited references establishes, by itself or in combination with other information, a prima facie case of unpatentability of any claim of the present case.

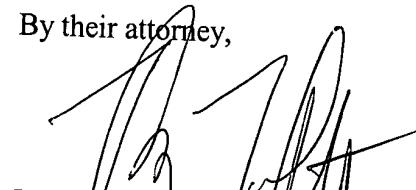
The information disclosure statement transmitted herewith is being filed after the mailing date of either a final action under §1.113 or a notice of allowance under §1.311, whichever occurs

first, but before payment of the issue fee.

Respectfully submitted,

Cabuz et al.

By their attorney,



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Dated: January 22, 2003